



Potting of electronic components
Telecommunication applications to avoid damage caused by moisture
Insulation of low voltage connections

Eigenschaften

- Resin can be removed very easily
- Free of iso-cyanates, epoxides and silicones
- Not classified according to the EC regulations
- Medium viscosity while pouring
- Good adhesion to metals, minerals and many plastics
- Excellent hydrophobic behaviour

Spezifikationen

Properties	Unit	Value
Potlife (process time) 20°C	minutes	20
Gel-time 20°C	minutes	50
Viscosity 20°C	cps	1000
Exothermic peak (ASTM D2471)	°C	28
Density	g / cm ³	0,91
Hardness	Shore A	5
Elongation at break	%	95
Temperature resistance	°C	80°C (short 120°C)
Corrosion of copper (MS 17000, 1139)		non corrosive
Insulation resistance at 500 V DC	ohm	1,2 x 10 ¹²
Volume resistivity bij 500 V DC	ohm.cm	0,6 x 10 ¹³
Water absorption (ASTM D570)	%	0,36
Water sensitivity (TA-NWT-000354)	%	0
Chemical resistant against		2n, H2SO4, CaCO3
colour		Transparent amber
Shelf life		18 months

Zusätzliche Informationen

[Download: Mixing instructions](#)

